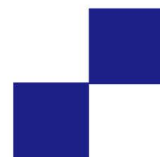




GLUE BROCHURE

DIRECTORY



HONGSI
Professional glue supplier

01

About us

Experienced Experienced

02

Service Introduction

Provide adhesive solutions.

03

Product details

Choose the appropriate adhesive.

01

About us



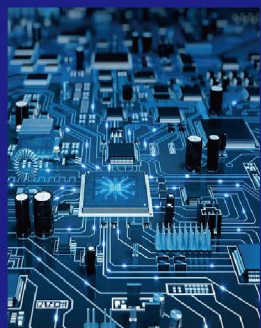
"We were established in 2012 and are dedicated to providing customers with high-quality, high-performance electronic and industrial-grade adhesives, as well as related optimized solutions."



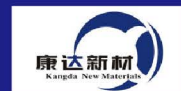
Our electronic-grade adhesive is widely used in bonding, encapsulation, insulation, and protection of electronic components. Our products are highly praised by customers for their reliability, durability, and advanced features.

We prioritize quality and customer satisfaction, adhering to the principle of "honest cooperation for mutual development." We maintain stable partnerships with suppliers to ensure that our electronic-grade adhesive meets international quality standards. We rigorously control quality in the selection and procurement of products.

We have a dedicated team with extensive knowledge and skills in the field of electronic-grade adhesive. From product selection and recommendations to pre-sales consultation and after-sales service, we are committed to providing customers with the best solutions and excellent service.



PARTNERS



Branch office service address

- 📍 Dongguan City, Guangdong Province, China
- 📍 Kunshan City, Suzhou, Jiangsu Province, China
- 📍 Hong Kong, China

02

Service Introduction

1

Provide adhesive solutions

We offer a variety of adhesive solutions to meet your needs. We provide customization options and offer professional advice to ensure the best fit. Our solutions are suitable for various materials and environmental conditions. Tell us your requirements, and we will find the most suitable solution to ensure the success of your project.

2

Adhesive validation service

We provide professional adhesive validation services to ensure optimal performance of your products. We conduct comprehensive testing and evaluation to meet project requirements and industry standards. Share your needs with us, and we will customize the validation process to guarantee the best quality and performance of your products.

03

Product details

SILICON ADHESIVE



Silicone bonding is a bonding method that uses silicone as an adhesive to firmly connect two surfaces together. It has excellent adhesive performance and high temperature resistance, can cure at room temperature, and is suitable for various material surfaces.

Three proof silicone is a specially designed sealing material used to protect electronic components from moisture, dust, and corrosion. It forms a strong barrier, effectively preventing external environmental damage to the equipment, ensuring its reliability and stability under harsh conditions.



• Silicone RTV silicone adhesive

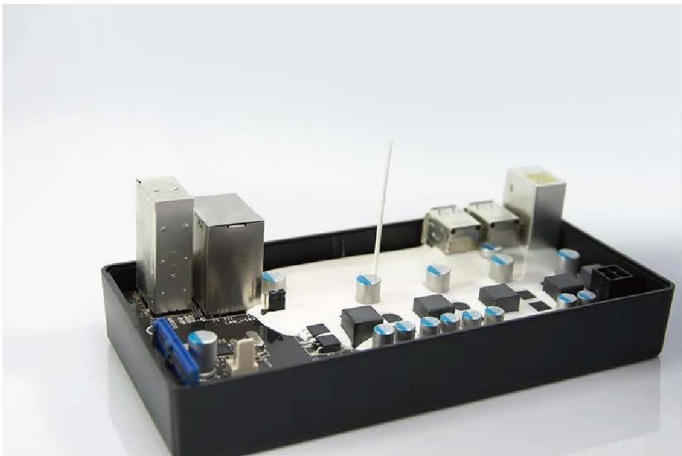
Model No	Color	Operating temperature	Dry-to-touch 25°C/min	Hardness	Shear strength (MPa)	Product description
6041	white	-40°C~200°C	5~30	shaoA 38±5	AL-AL ≥0.5	Resistant to water, high temperature, corrosion-free, excellent impact resistance, and durability.
HS-166	white	-40°C~220°C	5~30	shaoA 38±5	AL-AL ≥1.0	Neutral curing, resistant to water, high temperature, corrosion-free, and impact-resistant.
6003	white	-40°C~200°C	5~30	shaoA 38±5	AL-AL ≥1.0	Single-component flame-retardant silicone rubber sealant
503	Trans	-30°C~100°C	8~10	shaoA 45±5	AL-AL ≥2.5	Modified silane. Solvent-free, odorless, excellent adhesion to various plastic materials.

• Silicone silicone three proof adhesive

Model No	Color	Thermal conductivity W/m.K	Dry-to-touch 25°C/min	Hardness	Viscosity cP/25°C	Product description
1520	Semi-trans	$0.5 \times 10^{14} \Omega \cdot \text{cm}$	25~30	shaoD 20±5	400~1200	Abrasion-resistant, easy to spray or brush. Excellent adhesion to substrates and good dielectric properties.
1-2577	Semi-trans	$5E+13 \Omega \cdot \text{cm}$	8~10	shaoA 80±5	800~1000	Cures at room temperature, can also be heat-cured, with excellent moisture, weather, and salt spray resistance.
2577	Semi-trans	$4.4 \times 10^{15} \Omega \cdot \text{cm}$	5~10	shaoD 25±5	700~1000	Excellent moisture resistance, weather resistance, and salt spray resistance, able to withstand the impact of harsh environments.

THERMAL CONDUCTIVE SEALING ADHESIVE

Thermal potting adhesive is a low-viscosity, two-component organic silicone potting material. It possesses excellent fluidity, does not generate small molecules during curing, and exhibits outstanding thermal conductivity and insulation properties after solidification. It does not corrode various substrates and is primarily used for potting electronic components and circuit boards, such as drive power supplies, sensors, photovoltaic junction boxes, etc. It provides protection for electrical/electronic devices and components under harsh conditions such as high humidity, extreme temperatures, thermal cycling stress, mechanical shock and vibration, mold, dirt, etc. It offers seamless contact with heat-generating electronic components, allowing heat to conduct from the separated devices or the entire PCB to the metal casing or heat sink, thereby improving the efficiency and lifespan of heat-generating electronic components.



CHARACTERISTIC ADVANTAGES

- High thermal conductivity, low viscosity
- Good liquidity and rapid foaming
- Room temperature curing, can be heated to accelerate curing
- No corrosion to the substrate

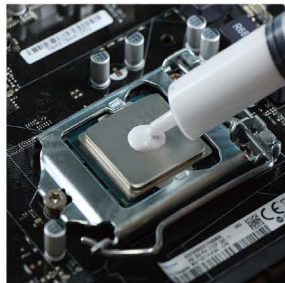
TYPICAL APPLICATIONS

- Sealing protection for power modules, inverters, and ballasts
- Sealing protection of electronic control units and sensors
- Sealing protection of LED lighting components
- Sealing purposes for other suitable products in the industrial field

• Silicone thermal sealing

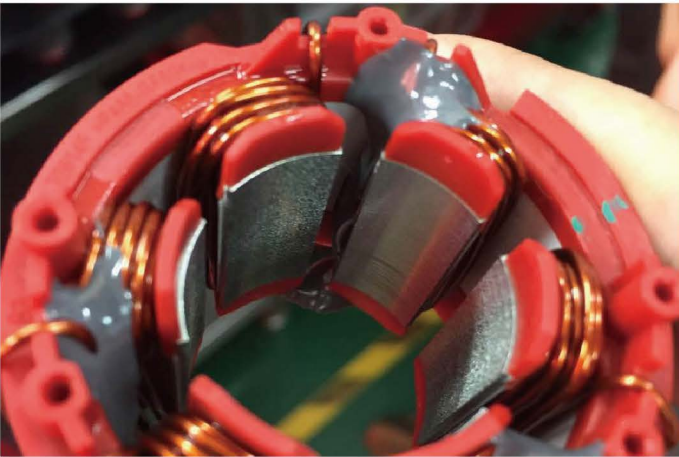
Model No	Color	Oper. time 25°C/min	Cure time 25°C/min	Thermal conductivity W/m.K	Volumetric resistivity	Hardness	Operating temperature	Flame retardancy	Mixed viscosity	Mixing ratio
1- 080	Gray	45	480	0.8±0.08	1*10 ¹⁴ Ω-cm	shaoA 50±5	-40~180°C	V-0	4000	1:1
150	Gray	60	480	1.5±0.15	2*10 ¹³ Ω-cm	shaoA 50±5	-40~180°C	V-0	7000	1:1
300	Gray	60	480	3.0±0.30	1*10 ¹³ Ω-cm	shaoA 50±5	-40~180°C	V-0	30000	1:1
498-12	Gray	120	1140	0.6±0.30	1*10 ¹³ Ω-cm	shaoD 85±5	-40~180°C	V-0	1600	100:10.4
400-64	black	40	1140	2.5±0.30	1*10 ¹⁵ Ω-cm	shaoD 90±5	-40~130°C	V-0	80000	100:3.75

• Other thermal conductive materials



EPOXY RESIN

Epoxy resin adhesive is a common adhesive composed of epoxy resin and curing agent. It has good adhesive properties and chemical resistance, forming a sturdy and durable connection after curing. Epoxy resin adhesive is suitable for various materials, including metals, plastics, ceramics, etc., and is widely used for bonding, sealing, and repair in industrial manufacturing, construction, aerospace, and other fields.



- Motor assembly, magnetic tile fixation, and inverter wire fixation



- Protecting electronic components, cable terminals, motors, sensors, LED beads



- Assembly of electronic heat sinks, LED lighting fixtures, power modules, semiconductor devices, etc



- Epoxy resin structural bonding

Model No	Product description	Mixed viscosity cPs@25°C	Curing conditions	Color	Product features
400-34	Single-component epoxy resin	150K~210K	120°C/120mins	Gray	Low hardness, high toughness
400-34HF	Single-component epoxy resin	130K~170K	120°C/135mins	Light gray	Low hardness, high toughness
400-36	Single-component epoxy resin	-	120°C/45mins	Dark gray	High tack strength magnetic core adhesive
400-36LH	Single-component epoxy resin	60K~90K	120°C/45mins	Gray	High tack strength magnetic core adhesive

- Epoxy resin - thermal conductive adhesive

Model No	Product description	Characteristics	Mixing ratio	Viscosity cP/25°C	Curing conditions
282A/B	Two-component epoxy (gray)	2W/mKhigh thermal conductivity	1:1	100K~120K	25°C24hrs/65°C2hrs
284/A/B	Two-component epoxy (black)	2W/mKhigh thermal conductivity	1:1	100K~150K	25°C24hrs/65°C2hrs
310-01	Single-component epoxy (black)	4.2W/mKhigh thermal conductivity	1:1	200K~300K	150°C30mins/125°C60mins

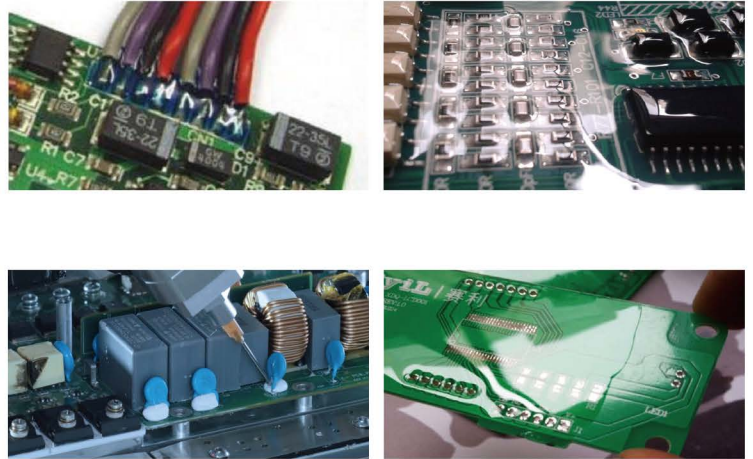
- Epoxy resin - potting and filling

Model No	Product description	Mixed viscosity cPs@25°C	Curing conditions	Color	Product features
2039A/B	Two-component epoxy potting adhesive	3K~5K	25°C24hrs/70°C1~2hrs	black	Low stress, high insulation
505-40A/B	Two-component epoxy potting adhesive	2K~4K	25°C12~16hrs	black	1:1 volume ratio, low viscosity
703-18A/B	Two-component epoxy potting adhesive	300~600	60°C4hrs	Trans	Ultra-low viscosity, transparent potting



UV adhesive

- Circuit fixation, solder protection, solder reinforcement, and component reinforcement



• Acrylic acid UV curing

Model No	Color	Viscosity cPs	Specific gravity g/cm ³	Curing	Hardness	Product description
UV147	Trans	4000~6000	1.05~1.10	1300mj/cm ²	shaoD 65	Good chemical resistance, good moisture resistance
UV150	Blue semi-trans	7000~12000	1.08~1.11	100mj/cm ²	shaoD 70	Fast low-energy curing, good adhesion to metal and glass
UV155	Semi-trans	2000~2600	1.10~1.15	400mj/cm ²	shaoD 75	No cracks under thermal shock, 100% solid, high transparency

• Acrylic acid UV+moisture curing

Model No	Color	Viscosity cPs	Specific gravity g/cm ³	UV and moisture	Moisture curing	Hardness	Operating temperature	Product features
UV-109	blue	7000~9000	1.05	30%RH/36hrs	30%RH/ < 7天	shaoD 67-76	-40°C~130°C	Moisture-proof, mildew-proof, dust-proof, salt spray resistant, acid and alkali resistant, high temperature and high humidity resistant
UV-146	Trans	13000~15000	1.10	30%RH/36hrs	30%RH/ < 7天	shaoD 76	-30°C~100°C	UV and moisture dual-curing adhesive, PEN bonding, protection of flexible wires, connection line fixing and reinforcement, etc.

Other categories of glue

FAST-DRYING ADHESIVE

Instant adhesive is typically a fast-drying adhesive with strong adhesion, commonly used for quick bonding needs. It typically cures within seconds to minutes and can be used to bond various materials such as metal, plastic, wood, etc.

HOT MELT ADHESIVE

Hot melt adhesive is a solid glue stick that turns into a liquid when heated with a hot glue gun, then applied to the objects to be bonded, and quickly cools and solidifies in a short time. It has strong adhesion and is suitable for bonding various materials, commonly used in crafts, packaging, repairs, and other fields.

ANAEROBIC ADHESIVE

Anaerobic adhesive is a special type of glue used for curing in an oxygen-free environment. It is typically employed to fill and seal tiny gaps on the surface of objects, as it doesn't require oxygen during the curing process, making it suitable for use in enclosed spaces. Anaerobic adhesive is commonly utilized for bonding between metals, such as in the assembly of mechanical components, as it provides enduring sealing and vibration resistance.

- Fast-drying adhesive

Model No	Viscosity cPs	Initial setting speed (S)	Haze	Main bonding substrates	Product features
DK63	2~5	3~8	relatively low	Plastic/rubber/silicone/TPR/inert elastomeric materials	Surface-insensitive, extremely fast curing, ideal for soft materials such as soft PVC, PU, TPR, silicone, etc.
DK67	2~8	12~20	low	PP/PU/TPE/TPR/Modified rubber	Low haze, inert plastic rubber free treatment bonding
DK208	200~300	15~30	low	PP/PU/TPE/TPR/Modified Rubber	Low haze, low viscosity, inert plastic rubber free treatment bonding

- Hot melt adhesive

Model No	Color	Viscosity (mPa*s) @110°C	Density	Open time	Application temperature	General application
9041	pale yellow	6500±1000	1.1 (g/cm³) @25°C	2-3 (min) @25°C	100~125°C	Bonding of various plastics, metals, glass, and other materials
6102	beige	7000±1000	1.15 (g/cm³) @25°C	5-8 (min) @25°C	110~120°C	Suitable for precision parts assembly industry, applicable to most materials such as aluminum, stainless steel, glass, etc.
P7524	light yellow	5000±1000	1.1 (g/cm³) @25°C	2-4 (min) @25°C	100~120°C	Structural bonding of electronic and electrical products

- Anaerobic adhesive

Model No	Color	Viscosity (cPs) @22°C	Curing speed (initial/complete)	Application temperature	Shear strength (MPa)	Product description
1326	Pale Yellow Trans	15000	1min./24hrs	-54°C~120°C	20.0	Single-component, high-viscosity anaerobic structural adhesive, with rapid curing, high strength, and resilient adhesive layer. Used for bonding rigid materials.
1680	green	1250	10min./24hrs	-60°C~150°C	23.2	Medium viscosity, high strength, excellent solvent resistance. Suitable for bonding and retaining various hole and shaft components with transition fits.
1243	blue	9000-17000	30min./24hrs	-60°C~150°C	25.0	Medium-strength product, removable, fast curing, thixotropic viscosity, also particularly suitable for use on slightly oily or inert surfaces.

WIN WIN COOPERATION TO CREATE BREATHE BRILLIANCE

CONTACT US

TEL: +84 788371421

E-mail: Kim@corbinvn.com.vn

Addr: 125/41 Nguyen Van Thuong, 25 Ward, Binh Thanh District, Ho Chi Minh city



CORBIN IDUSTRY COMPANY LIMITED
CÔNG TY TNHH CÔNG NGHIỆP CORBIN.